

Title (en)  
Silicone grease compositions

Title (de)  
Silikonfett-Zusammensetzung

Title (fr)  
Composition de graisse de silicone

Publication  
**EP 1600494 B1 20180829 (EN)**

Application  
**EP 05253144 A 20050520**

Priority  
• JP 2004151706 A 20040521  
• JP 2004299616 A 20041014

Abstract (en)  
[origin: EP1600494A1] A silicone grease composition is provided comprising (A) 2-40% by weight of an organopolysiloxane having a kinematic viscosity of 50-500,000 mm<sup>2</sup>/s at 25 DEG C, and (B) 60-98% by weight of at least one heat conductive filler selected from among metal powders, metal oxide powders and ceramic powders having a thermal conductivity of at least 10 W/m DEG C and an average particle size of 0.1-15.0  $\mu$ m. Coarse particles are removed such that a 500-mesh oversize fraction is not more than 50 ppm and a 325-mesh oversize fraction is substantially zero.

IPC 8 full level  
**C10M 111/04** (2006.01); **C08L 83/04** (2006.01); **C10M 169/02** (2006.01)

CPC (source: EP KR US)  
**C08L 83/04** (2013.01 - EP US); **C10M 105/76** (2013.01 - KR); **C10M 107/50** (2013.01 - KR); **C10M 111/04** (2013.01 - EP US); **C10M 169/02** (2013.01 - EP KR US); **C10M 2201/05** (2013.01 - EP US); **C10M 2201/053** (2013.01 - EP US); **C10M 2201/062** (2013.01 - EP US); **C10M 2201/0623** (2013.01 - EP US); **C10M 2201/10** (2013.01 - EP US); **C10M 2201/1006** (2013.01 - EP US); **C10M 2229/0405** (2013.01 - EP US); **C10M 2229/0415** (2013.01 - EP US); **C10N 2010/02** (2013.01 - EP US); **C10N 2010/04** (2013.01 - EP US); **C10N 2010/06** (2013.01 - EP US); **C10N 2020/01** (2020.05 - EP US); **C10N 2020/02** (2013.01 - EP US); **C10N 2030/02** (2013.01 - EP US); **C10N 2040/14** (2013.01 - EP US)

Cited by  
EP1985691A1; JP2012052137A; EP2194581A1; EP2565160A4; EP1803798A3; CN103923463A; US8017684B2; WO2010127215A1; US7786056B2; JP2007177001A

Designated contracting state (EPC)  
DE FR GB

DOCDB simple family (publication)  
**EP 1600494 A1 20051130; EP 1600494 B1 20180829**; KR 101125811 B1 20120328; KR 20060048037 A 20060518; TW 200613541 A 20060501; TW I385246 B 20130211; US 2005261140 A1 20051124; US 7510998 B2 20090331

DOCDB simple family (application)  
**EP 05253144 A 20050520**; KR 20050042314 A 20050520; TW 94116167 A 20050518; US 13333905 A 20050520